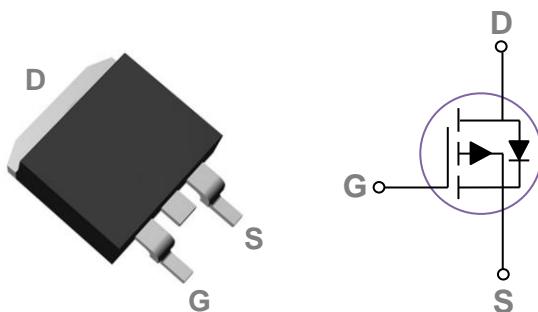


### General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### TO263 Pin Configuration



BVDSS	RDS(ON)	ID
-100V	41mΩ	-35A

### Features

- -100V,-35A, RDS(ON) 41mΩ@VGS = -10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Networking
- Load Switch
- LED applications

### Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
Vds	Drain-Source Voltage	-100	V
Vgs	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>c</sub> =25°C)	-35	A
	Drain Current – Continuous (T <sub>c</sub> =100°C)	-22	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	-140	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	180	mJ
I <sub>AS</sub>	Single Pulse Avalanche Current <sup>2</sup>	-60	A
P <sub>D</sub>	Power Dissipation (T <sub>c</sub> =25°C)	142	W
	Power Dissipation – Derate above 25°C	1.14	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	0.88	°C/W

**Electrical Characteristics ( $T_J=25\text{ }^{\circ}\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=-250\mu\text{A}$	-100	---	---	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-80\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	-1	$\mu\text{A}$
		$V_{DS}=-80\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=85\text{ }^{\circ}\text{C}$	---	---	-10	$\mu\text{A}$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}$ , $I_D=-15\text{A}$	---	34	41	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$ , $I_D=-10\text{A}$	---	44	57	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D = -250\mu\text{A}$	-1.2	-1.6	-2.5	V

**Dynamic and switching Characteristics<sup>3</sup>**

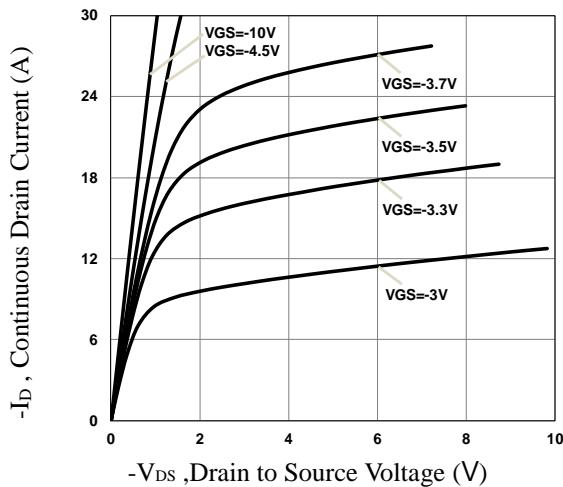
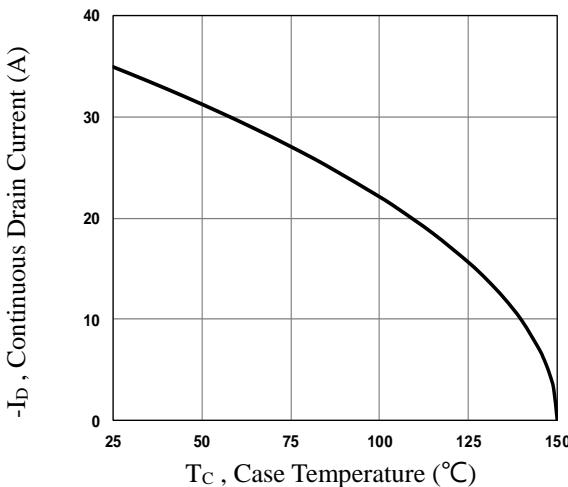
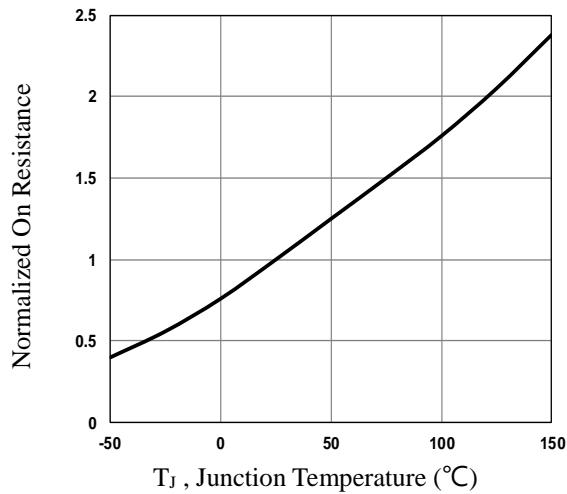
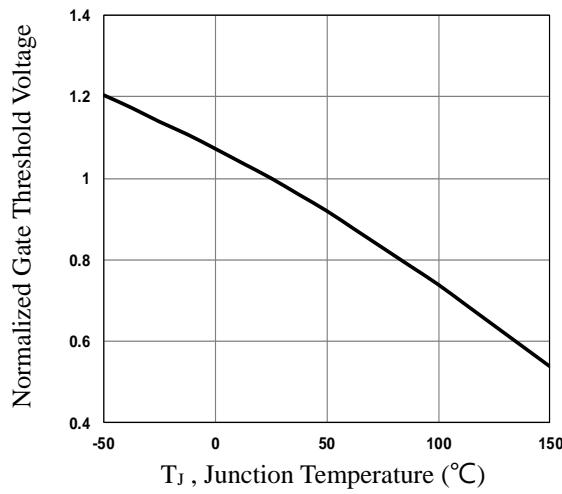
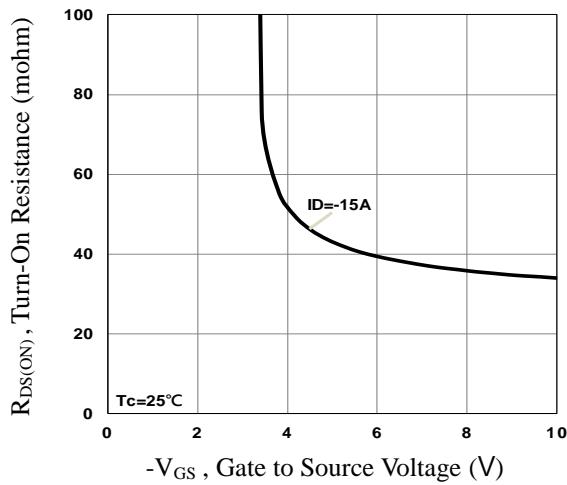
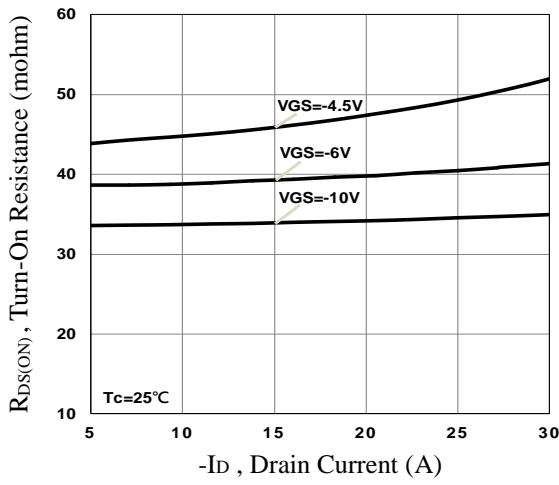
$Q_g$	Total Gate Charge	$V_{DS}=-50\text{V}$ , $V_{GS}=-10\text{V}$ , $I_D=-15\text{A}$	---	22	35	nC
$Q_{gs}$	Gate-Source Charge	$V_{DS}=-50\text{V}$ , $V_{GS}=-4.5\text{V}$ , $I_D=-15\text{A}$	---	11	16.5	
$Q_{gd}$	Gate-Drain Charge		---	1	3	
$Q_{gd}$	Gate-Drain Charge		---	4.4	7	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=-50\text{V}$ , $V_{GS}=-10\text{V}$ , $R_G=6\Omega$ $I_D=-15\text{A}$	---	3	5	ns
$T_r$	Rise Time		---	5	8	
$T_{d(off)}$	Turn-Off Delay Time		---	6	10	
$T_f$	Fall Time		---	15	25	
$C_{iss}$	Input Capacitance	$V_{DS}=-50\text{V}$ , $V_{GS}=0\text{V}$ , $F=1\text{MHz}$	---	1300	1950	pF
$C_{oss}$	Output Capacitance		---	340	500	
$C_{rss}$	Reverse Transfer Capacitance		---	12	20	

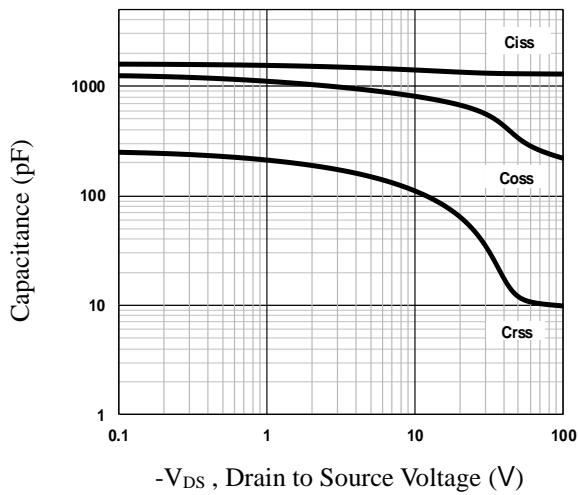
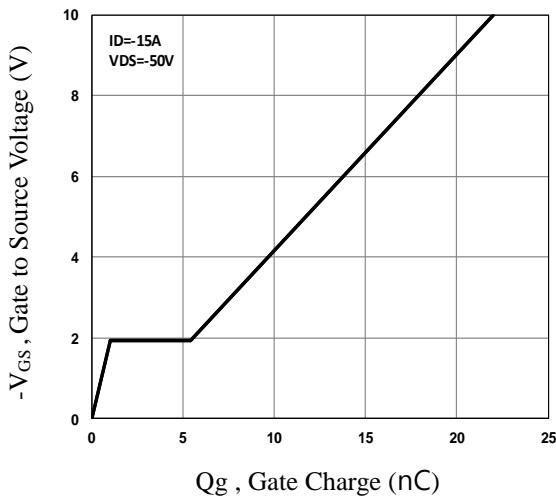
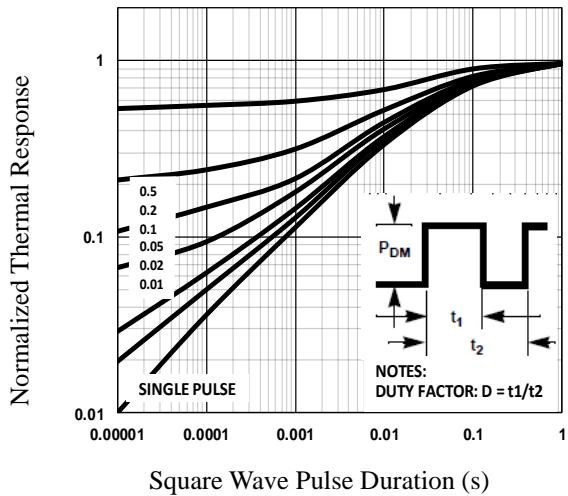
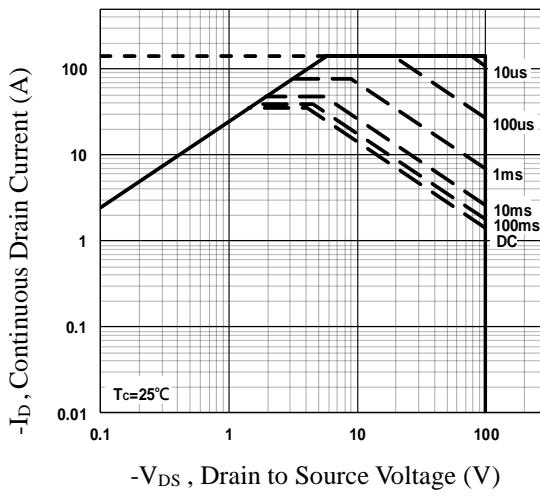
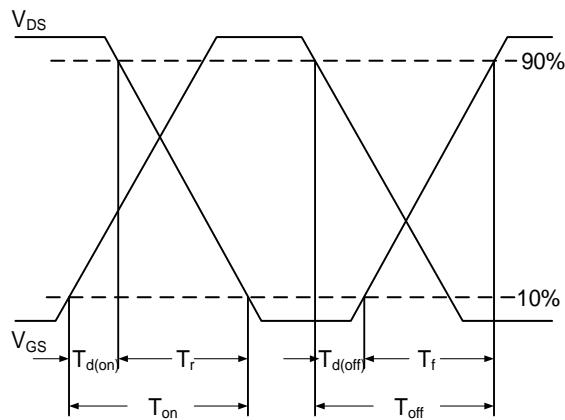
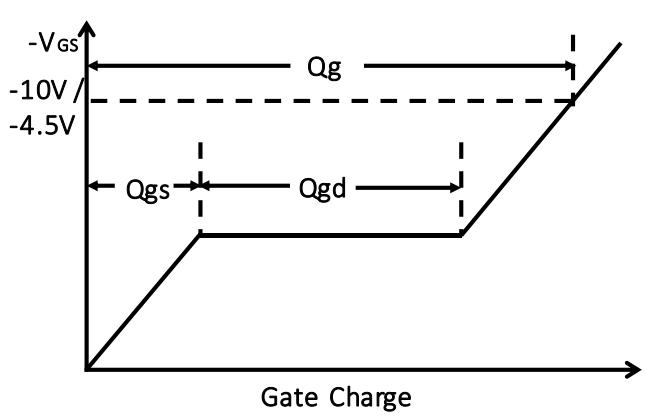
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	-35	A
			---	---	-70	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	-1	V
$t_{rr}$	Reverse Recovery Time	$V_R=-100\text{V}$ , $I_s=-10\text{A}$ $di/dt=100\text{A}/\mu\text{s}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	170	---	ns
$Q_{rr}$	Reverse Recovery Charge		---	540	---	nC

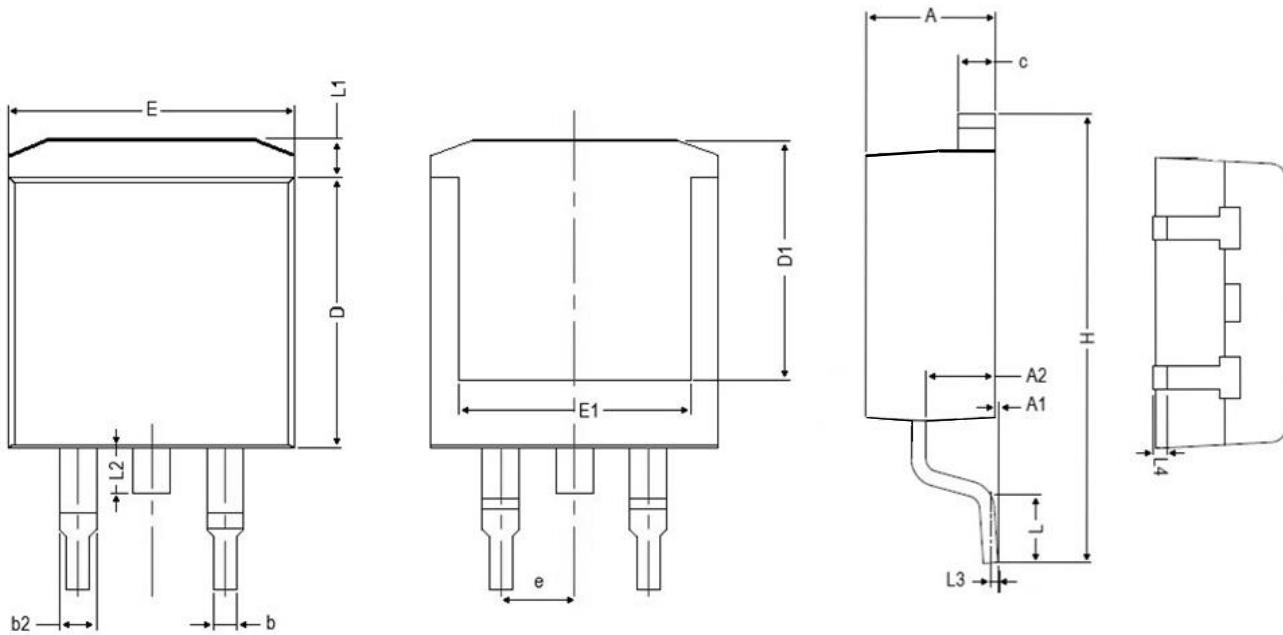
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=-50\text{V}$ ,  $V_{GS}=-10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{AS}=-60\text{A}$ , Starting  $T_J=25\text{ }^{\circ}\text{C}$
3. Essentially independent of operating temperature.


**Fig.1 Typical Output Characteristics**

**Fig.2 Continuous Drain Current vs.  $T_c$** 

**Fig.3 Normalized  $R_{DS(ON)}$  vs.  $T_J$** 

**Fig.4 Normalized  $V_{th}$  vs.  $T_J$** 

**Fig.5 Turn-On Resistance vs.  $V_{GS}$** 

**Fig.6 Turn-On Resistance vs.  $I_D$**


**Fig.7 Capacitance Characteristics**

**Fig.8 Gate Charge Characteristics**

**Fig.9 Normalized Transient Impedance**

**Fig.10 Maximum Safe Operation Area**

**Fig.11 Switching Time Waveform**

**Fig.12 Gate Charge Waveform**

## TO263 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	4.850	4.200	0.191	0.165
A1	0.300	0.000	0.012	0.000
A2	2.900	2.200	0.114	0.087
b	0.950	0.700	0.037	0.028
b2	1.700	1.000	0.067	0.039
c	1.450	1.150	0.057	0.045
D	9.500	8.350	0.374	0.329
D1	9.150	6.400	0.360	0.252
E	10.500	9.600	0.413	0.378
E1	8.900	6.850	0.350	0.270
e	2.540 BSC		0.100 BSC	
H	15.900	14.600	0.626	0.575
L	2.800	1.700	0.110	0.067
L1	1.700	1.050	0.067	0.041
L2	2.100	1.300	0.083	0.051
L3	0.250 BSC		0.010 BSC	
L4	0.750	0.200	0.030	0.008